



(0.80 mm) .0315"

HSEC8-120-01-L-RA

HSEC8-160-01-L-RA-BL

HSEC8-RA SERIES

RIGHT-ANGLE EDGE RATE® CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/HSEC8-RA

Insulator Material:

Black Liquid Crystal Polymer

Contact:

BeCu

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:

2.6 A per pin

(2 adjacent pins powered)

Operating Temp:

-55 °C to +125 °C

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (10-60)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594



FILE NO. 990871_0_000

ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.

Card Mates:
(1.60 mm) .062" thick card,
HSC8

Cable Mates:
ECDP

Rugged
Edge Rate®
contacts
designed for
Signal Integrity



Accepts (1.60 mm) .062"
PCB thicknesses

Optional
Board
Locks

RUGGEDIZED
BY SAMTEC

• Board lock option

HSEC8

1

POSITIONS
PER ROWCARD
THICKNESSPLATING
OPTION

RA

OTHER
OPTION

09, 10, 13, 20, 25,
30, 40, 49, 50, 60

-01
= (1.60 mm) .062"
thick card

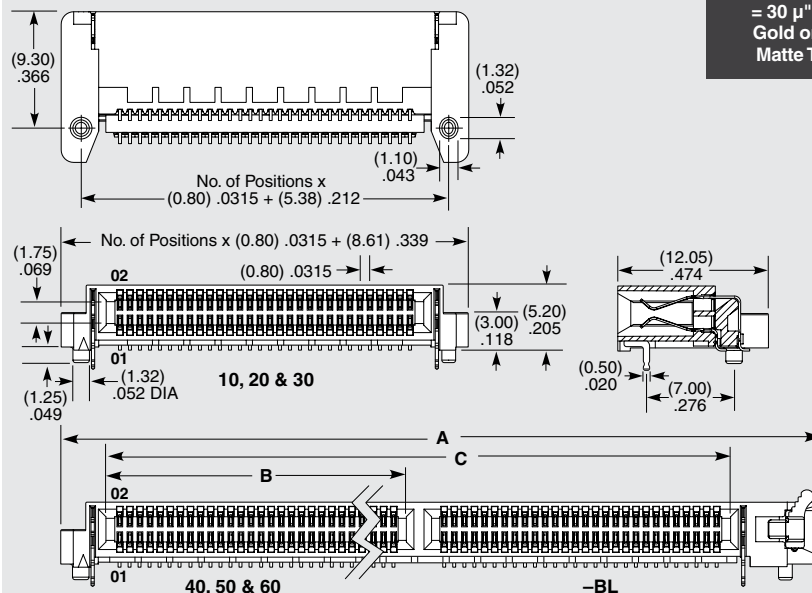
-L
= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail

-S
= 30 μ" (0.76 μm)
Gold on contact,
Matte Tin on tail

-BL
= Board Locks
(09, 13, 25, 40,
49, 50, 60 only)

-L2
= ECDP Latching
(09, 13, 25,
49 only)
(For use with
ECDP)

-TR
= Tape & Reel
Packaging
(10 thru 60
positions only)



POSITIONS PER ROW	A	B	C
40	(43.80) 1.724	(18.90) .744	(36.60) 1.441
50	(51.80) 2.039	(22.90) .902	(44.60) 1.756
60	(59.80) 2.354	(26.90) 1.059	(52.60) 2.071
40-BL	(51.30) 2.020	(18.90) .744	(36.60) 1.441
50-BL	(59.30) 2.335	(22.90) .902	(44.60) 1.756
60-BL	(67.30) 2.650	(26.90) 1.059	(52.60) 2.071

Notes:
While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.

Some lengths, styles and options are non-standard, non-returnable.